

P-Ch MOSFET

## **General Description**

The WSC80P03 is the highest performance trench P-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSC80P03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

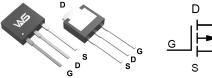
## **Product Summery**

BVDSS	RDSON	ID
-30V	5.4mΩ	-75A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

# **TO-251 Pin Configuration**





## **Absolute Maximum Ratings**

		Ra	Rating		
Symbol	Parameter	10s	Steady State	Units	
$V_{DS}$	Drain-Source Voltage	=:	-30		
$V_{GS}$	Gate-Source Voltage	<u>±</u>	±20		
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>		75	Α	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-1	-60		
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-22	-18	Α	
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-18	-14	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-280		Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	415		mJ	
I <sub>AS</sub>	Avalanche Current	-58		Α	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	50		W	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	5	2.5	W	
T <sub>STG</sub>	Storage Temperature Range	-55 t	-55 to 175		
T <sub>J</sub>	Operating Junction Temperature Range -55 to 175		$^{\circ}$		

# **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤10s)		25	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		2.4	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =-1mA		-0.018		V/°C
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-30A		5.4	9	
R <sub>DS(ON)</sub>	Static Dialii-Source Off-Resistance	V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-15A		8.9	15	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . I <sub>D</sub> =-250uA	-1.5	-1.8	-3.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250UA		5.04		mV/℃
	Drain Source Leakage Current	$V_{DS}$ =-24V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	- uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	$V_{DS}$ =-5V , $I_{D}$ =-20A		36		S
$Q_g$	Total Gate Charge (-4.5V)			93		
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-24A		15		nC
$Q_{gd}$	Gate-Drain Charge			19		
T <sub>d(on)</sub>	Turn-On Delay Time			38		
Tr	Rise Time	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V ,		17		no
$T_{d(off)}$	Turn-Off Delay Time	$R_G$ =3.3 $\Omega$ , $I_D$ =-15A ,RL=0.62 $\Omega$		139		ns ns
T <sub>f</sub>	Fall Time			37		
C <sub>iss</sub>	Input Capacitance			5554		
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		761		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			435		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.1mH , I <sub>AS</sub> =-30A	120			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-75	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				-280	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{S}$ =-1A , $T_{J}$ =25 $^{\circ}$ C			-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	IF=-15A,dI/dt=100A/µs, T <sub>J</sub> =25℃		33		nS
Q <sub>rr</sub>	Reverse Recovery Charge			18		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =-25V,  $V_{GS}$ =-10V,L=0.1mH,  $I_{AS}$ =-30A
- 4. The power dissipation is limited by 150 °C junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- $6. The \ data \ is \ theoretically \ the \ same \ as \ I_D \ and \ I_{DM} \ , \ in \ real \ applications \ , \ should \ be \ limited \ by \ total \ power \ dissipation.$



#### **Typical Characteristics**

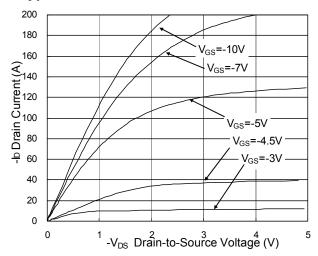


Fig.1 Typical Output Characteristics

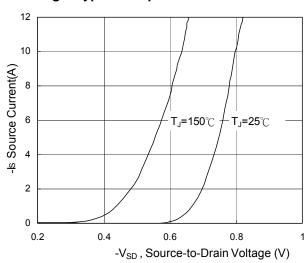


Fig.3 Forward Characteristics Of Reverse

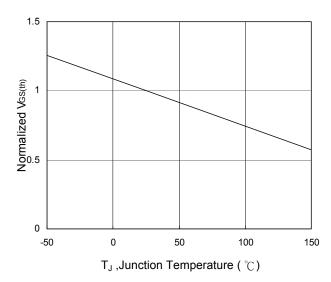


Fig.5 Normalized V<sub>GS(th)</sub> v.s T<sub>J</sub>

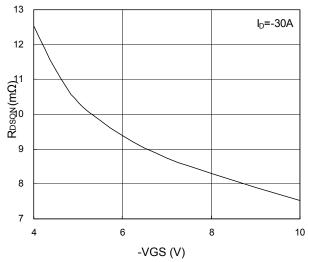


Fig.2 On-Resistance v.s Gate-Source

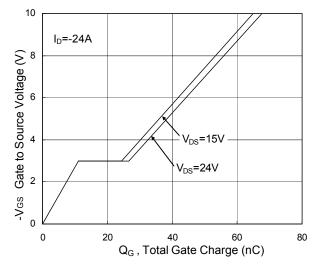


Fig.4 Gate-Charge Characteristics

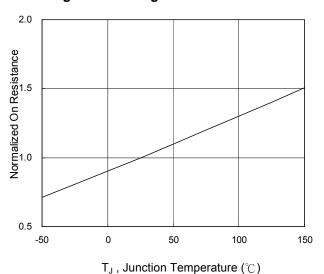
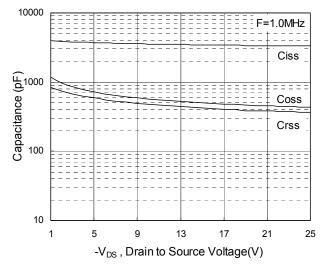


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>







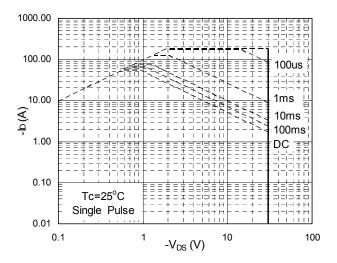


Fig.7 Capacitance

Fig.8 Safe Operating Area

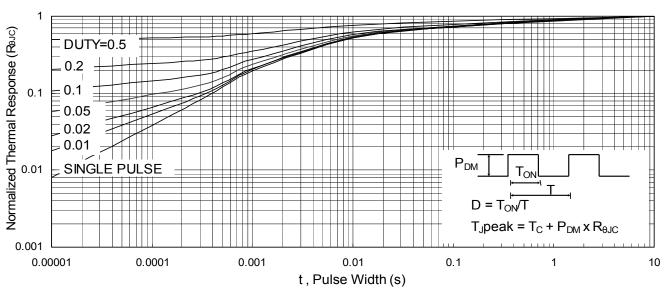


Fig.9 Normalized Maximum Transient Thermal Impedance

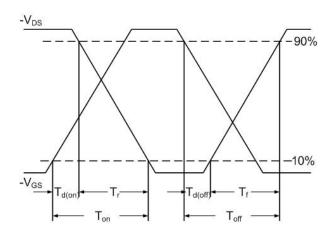


Fig.10 Switching Time Waveform

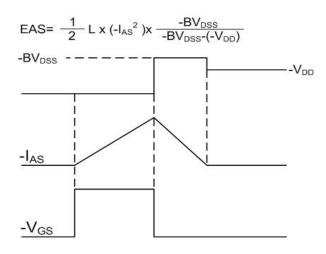


Fig.11 Unclamped Inductive Switching Waveform



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